

## Initial Product/Process Change Notification Document #:IPCN23907Y

Document #: IPCN23907Y Issue Date: 28 Jul 2021

Title of Change:	J-Series Solder Resist Change			
Proposed First Ship date:	01 Feb 2022 or earlier if approved by customer			
Contact Information:	Contact your local ON Semiconductor Sales Office or <a href="Deborah.Herbert@onsemi.com">Deborah.Herbert@onsemi.com</a>			
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or < <a href="PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> >.  Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.  Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com>			
Marking of Parts/ Traceability of Change:	No marking - traceability will be lot date code			
Change Category:	Wafer Fab Change			
Change Sub-Category(s):	Manufacturing Process Change			
Sites Affected:				
ON Semiconductor Sites	External Foundry/Subcon Sites			
None	JSC, Japan Semiconductor			

### **Description and Purpose:**

The solder resist material on the back of the TSV package is being changed. The change will be visible but is not expected to affect performance.

	Before Change Description	After Change Description
	Model: SS-0300	Model: WPR-1203
Solder Resist Material	Type: IR Cut	Type: Non-IR Cut
	Thickness: 23 μm	Thickness: 11.5 μm

There is no product marking change as a result of this change.

#### **Qualification Plan:**

QV DEVICE NAME: MicroFJ-60035-TSV

PACKAGE: TSV

Test	Specification	Condition	Interval	
HTRB	JESD22-A108	Ta=85°C, max rated V	1000hrs	
HTSL	JESD22-A103	Ta= 125°C	264hrs	
TC	JESD22-A104	Ta= -40°C to +85°C	500cyc	
PC	J-STD-020 JESD-A113	MSL3		
RSH	JESD22- B106	Ta = 265C, 10 sec		

Estimated date for qualification completion: 31-Oct-21

The MicroFJ-600335-TSV is used as the qualification vehicle for all parts.

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#### **List of Affected Parts:**

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer  $specific \ PCN \ addendum \ in \ the \ PCN \ email \ notification, \ or \ on \ the \ \underline{PCN \ Customized \ Portal}.$ 

Part Number	Qualification Vehicle
MICROFJ-60035-TSV-TR	NA
MICROFJ-60035-TSV-TR1	NA
MICROFJ-40035-TSV-TR	NA
MICROFJ-40035-TSV-TR1	NA
MICROFJ-30035-TSV-TR	NA
MICROFJ-30035-TSV-TR1	NA

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